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APPLICATION NO.	FILING DATE	FIRST NAMED INVENTOR	ATTORNEY DOCKET NO.	CONFIRMATION NO.
10/788,730	02/27/2004	Yonjun Jeff Hu	400.084US02	8506
27073	7590 05/03/2005	EXAMINER		
LEFFERT JAY & POLGLAZE, P.A. P.O. BOX 581009			COLEMAN, WILLIAM D	
				
MINNEAPOLIS, MN 55458-1009			ART UNIT	PAPER NUMBER
			2823	
			DATE MAILED: 05/03/2005	

Please find below and/or attached an Office communication concerning this application or proceeding.

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	Application No.	Applicant(s)				
	10/788,730	HU, YONJUN JEFF :				
Office Action Summary	Examiner	Art Unit				
	W. David Coleman	2823				
The MAILING DATE of this communication ap Period for Reply	pears on the cover sheet with the c	orrespondence address				
A SHORTENED STATUTORY PERIOD FOR REPL THE MAILING DATE OF THIS COMMUNICATION. - Extensions of time may be available under the provisions of 37 CFR 1. after SIX (6) MONTHS from the mailing date of this communication. - If the period for reply specified above is less than thirty (30) days, a replication of the period for reply is specified above, the maximum statutory period. Failure to reply within the set or extended period for reply will, by statut Any reply received by the Office later than three months after the mailinearned patent term adjustment. See 37 CFR 1.704(b).	136(a). In no event, however, may a reply be timely within the statutory minimum of thirty (30) days will apply and will expire SIX (6) MONTHS from the cause the application to become ABANDONE	nely filed : s will be considered timely. the mailing date of this communication. D (35 U.S.C. § 133).				
Status		» .				
1) Responsive to communication(s) filed on 27 F	- ebruary 2004.					
•						
	Since this application is in condition for allowance except for formal matters, prosecution as to the merits is closed in accordance with the practice under <i>Ex parte Quayle</i> , 1935 C.D. 11, 453 O.G. 213.					
Disposition of Claims						
4) Claim(s) 1-54 is/are pending in the application. 4a) Of the above claim(s) is/are withdrawn from consideration. 5) Claim(s) 23-31 and 49-54 is/are allowed. 6) Claim(s) 1-22 and 32-48 is/are rejected. 7) Claim(s) is/are objected to. 8) Claim(s) are subject to restriction and/or election requirement.						
Application Papers		٠				
9) The specification is objected to by the Examin 10) The drawing(s) filed on is/are: a) ac Applicant may not request that any objection to the Replacement drawing sheet(s) including the correct 11) The oath or declaration is objected to by the E	cepted or b) objected to by the E e drawing(s) be held in abeyance. See ction is required if the drawing(s) is obj	e 37 CFR 1.85(a). jected to. See 37 CFR 1.121(d).				
Priority under 35 U.S.C. § 119						
12) Acknowledgment is made of a claim for foreign priority under 35 U.S.C. § 119(a)-(d) or (f). a) All b) Some * c) None of: 1. Certified copies of the priority documents have been received. 2. Certified copies of the priority documents have been received in Application No. 3. Copies of the certified copies of the priority documents have been received in this National Stage application from the International Bureau (PCT Rule 17.2(a)). * See the attached detailed Office action for a list of the certified copies not received.						
Attachment(s) 1) Notice of References Cited (PTO-892) 2) Notice of Draftsperson's Patent Drawing Review (PTO-948) 3) Information Disclosure Statement(s) (PTO-1449 or PTO/SB/08 Paper No(s)/Mail Date 02/04	4) Interview Summary Paper No(s)/Mail Da 5) Notice of Informal P 6) Other:					

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DETAILED ACTION

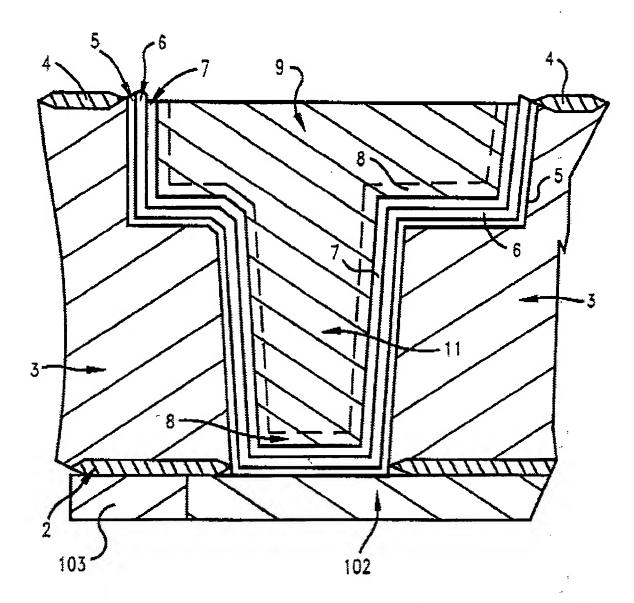
Claim Rejections - 35 USC § 102

1. The following is a quotation of the appropriate paragraphs of 35 U.S.C. 102 that form the basis for the rejections under this section made in this Office action:

A person shall be entitled to a patent unless -

- (e) the invention was described in a patent granted on an application for patent by another filed in the United States before the invention thereof by the applicant for patent, or on an international application by another who has fulfilled the requirements of paragraphs (1), (2), and (4) of section 371(c) of this title before the invention thereof by the applicant for patent.
- 2. The changes made to 35 U.S.C. 102(e) by the American Inventors Protection Act of 1999 (AIPA) and the Intellectual Property and High Technology Technical Amendments Act of 2002 do not apply when the reference is a U.S. patent resulting directly or indirectly from an international application filed before November 29, 2000. Therefore, the prior art date of the reference is determined under 35 U.S.C. 102(e) prior to the amendment by the AIPA (pre-AIPA 35 U.S.C. 102(e)).
- 3. Claims 1, 2, 3, 4, 5, 6, 7, 11, 12, 13, 14, 15, 16, 17, 32, 33, 34, 35 and 36 are rejected under 35 U.S.C. 102(e) as being anticipated by Rathore et al., U.S. Patent 6,258,710 B.1.
- 4. <u>Rathore</u> discloses a semiconductor device as claimed. See **FIGS. 1-8** where <u>Rathore</u> teaches the following limitations.

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- 5. Pertaining to claim 1, <u>Rathore</u> teaches an interconnect of an integrated circuit device, comprising.
- a diffusion barrier layer 5;

a first metal layer on the diffusion barrier layer 6/7, wherein the first metal layer comprises a first metal component and a second metal component 8 forming a crystalline compound with the first metal component, wherein the second metal component has a surface energy lower than a

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surface energy of the first metal component, and wherein the crystalline compound is rich in the

first metal component; and

a second metal layer on the first metal layer, wherein the second metal layer comprises the first

metal component.

6. Pertaining to claim 2, Rathore teaches the interconnect of claim 1, wherein the diffusion

barrier layer is a titanium-containing layer.

7. Pertaining to claim 3, Rathore the interconnect of claim 1, wherein the diffusion barrier

layer is titanium nitride.

8. Pertaining to claim 4, Rathore teaches the interconnect of claim 1, wherein the first metal

component is selected from the group consisting of copper, silver, gold, palladium, platinum,

rhenium, iridium, ruthenium and osmium.

9. Pertaining to claim 5, Rathore The interconnect of claim 1, wherein the second metal

component is selected from the group consisting of scandium, yttrium, lanthanum, titanium,

zirconium and hafnium.

10. Pertaining to claim 6, Rathore teaches the interconnect of claim 1, wherein the first metal

layer further comprises a third metal component forming a second crystalline compound with the

first metal component, wherein the third metal component is different from the second metal

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component, wherein the third metal component has a surface energy lower than a surface energy of the first metal component, and wherein the second crystalline compound is rich in the first metal component.

- 11. Pertaining to claim 7, <u>Rathore</u> teaches a portion of an integrated circuit device, comprising:
- a dielectric layer overlying a base layer; a layer of titanium nitride overlying the dielectric layer; a first metal layer on the layer of titanium nitride, wherein the first metal layer comprises a crystalline alloy compound containing a first metal component and a second metal component, wherein the second metal component is selected from the group consisting of Group IIIA and Group IVA elements, and wherein an atomic ratio of the first metal component to the second metal component in the first metal layer is greater than one; and a second metal layer on the first metal layer, wherein the second metal layer comprises the first metal component.
- 12. Pertaining to claim 11, <u>Rathore</u> teaches the portion of an integrated circuit device of claim 7, wherein the layer of titanium nitride is adjoining a portion of the dielectric layer.
- 13. Pertaining to claim 12, <u>Rathore</u> teaches the portion of an integrated circuit device of claim 11, wherein the layer of titanium nitride is further adjoining a portion of the base layer.

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14. Pertaining to claim 13, <u>Rathore</u> teaches the portion of an integrated circuit device of

claim 7, wherein the base layer is selected from the group consisting of a semiconductor

substrate and a conductor layer.

15. Pertaining to claim 14, Rathore teaches an interconnect of an integrated circuit device,

comprising:

a titanium nitride layer;

a first metal layer on the titanium nitride layer, wherein the first metal layer comprises copper

and a metal component forming a crystalline compound with the copper, wherein the metal

component is selected from the group consisting of scandium, yttrium, lanthanum, titanium,

zirconium and hafnium, and wherein the crystalline compound has an atomic ratio of copper to

the metal component in the first metal layer of greater than one; and

a second metal layer on the first metal layer, wherein the second metal layer comprises copper.

16. Pertaining to claim 15, Rathore teaches a portion of an integrated circuit device,

comprising:

a layer of titanium nitride adjoining a dielectric layer;

a metal layer on the layer of titanium nitride, wherein the metal layer comprises a

copper-rich alloy selected from the group consisting of Cu4Sc, Cu6Y, Cu4Ti,

Cu3Ti and CuSZr; and

a copper layer on the metal layer.

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17. Pertaining to claim 16, <u>Rathore</u> teaches the portion of an integrated circuit device of

claim 15, wherein the copper-rich alloy has a crystalline structure.

18. Pertaining to claim 17, Rathore teaches the portion of an integrated circuit device of

claim 15, wherein the metal layer further comprises elemental copper.

19. Pertaining to claim 32, Rathore teaches an interconnect of an integrated circuit device,

comprising:

a diffusion barrier layer;

a nitrided metal layer on the diffusion barrier layer, wherein the nitrided metal layer

comprises a first metal component, a second metal component capable of

forming a crystalline compound with the first metal component, and

nitrogen, wherein the second metal component has a surface energy lower

than a surface energy of the first metal component, and wherein the nitrided

metal layer is rich in the first metal component; and

a second metal layer on the nitrided metal layer, wherein the second metal layer

comprises the first metal component.

20. Pertaining to claim 33, Rathore teaches The interconnect of claim 32, wherein the

diffusion barrier layer is a titanium containing layer.

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- 21. Pertaining to claim 34, <u>Rathore</u> teaches the interconnect of claim 32, wherein the diffusion barrier layer is titanium nitride.
- 22. Pertaining to claim 35, <u>Rathore</u> teaches the interconnect of claim 32, wherein the first metal component is selected from the group consisting of copper, silver, gold, palladium, platinum, rhenium, iridium, ruthenium and osmium.
- 23. Pertaining to claim 36, <u>Rathore</u> teaches the interconnect of claim 32, wherein the second metal component is selected from the group consisting of scandium, yttrium, lanthanum, titanium, zirconium and hafnium.

Claim Rejections - 35 USC § 103

- 24. The following is a quotation of 35 U.S.C. 103(a) which forms the basis for all obviousness rejections set forth in this Office action:
 - (a) A patent may not be obtained though the invention is not identically disclosed or described as set forth in section 102 of this title, if the differences between the subject matter sought to be patented and the prior art are such that the subject matter as a whole would have been obvious at the time the invention was made to a person having ordinary skill in the art to which said subject matter pertains. Patentability shall not be negatived by the manner in which the invention was made.
- 25. Claims 8, 9, 10, 18, 19, 20, 21, 22 and 37-48 are rejected under 35 U.S.C. 103(a) as being unpatentable over Rathore et al., U.S. Patent 6,258,710 B1.
- 26. Given the teaching of the references, it would have been obvious to determine the optimum thickness, temperature as well as condition of delivery of the layers involved. See *In re Aller, Lacey and Hall* (10 USPQ 233-237) "It is not inventive to discover optimum or workable ranges by routine experimentation. Note that the specification contains no disclosure of either the critical nature of the claimed ranges or any unexpected results arising therefrom. Where

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patentability is said to be based upon particular chosen dimensions or upon another variable recited in a claim, the Applicant must show that the chosen dimensions are critical. *In re Woodruff*, 919 f.2d 1575, 1578, 16 USPQ2d 1934, 1936 (Fed. Cir. 1990).

Any differences in the claimed invention and the prior art may be expected to result in some differences in properties. The issue is whether the properties differ to such an extent that the difference is really unexpected. *In re Merck & Co.*, 800 F.2d 1091, 231 USPQ 375 (Fed. Cir. 1986)

Appellants have the burden of explaining the data in any declaration they proffer as evidence of non-obviousness. *Ex parte Ishizaka*, 24 USPQ2d 1621, 1624 (Bd. Pat. App. & Inter. 1992).

An Affidavit or declaration under 37 CFR 1.132 must compare the claimed subject matter with the closest prior art to be effective to rebut a prima facie case of obviousness. *In re Burckel*, 592 F.2d 1175, 201 USPQ 67 (CCPA 1979).

Allowable Subject Matter

- 27. Claims 23-31 and 49-54 allowed.
- 28. The following is an examiner's statement of reasons for allowance: the prior art does not anticipate nor render obviousness as to providing a silver layer for the integrated circuit.
- 29. Any comments considered necessary by applicant must be submitted no later than the payment of the issue fee and, to avoid processing delays, should preferably accompany the issue fee. Such submissions should be clearly labeled "Comments on Statement of Reasons for Allowance."

Conclusion

30. Any inquiry concerning this communication or earlier communications from the examiner should be directed to W. David Coleman whose telephone number is 571-272-1856. The examiner can normally be reached on Monday-Friday 9:00 AM - 5:30 PM.

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31. If attempts to reach the examiner by telephone are unsuccessful, the examiner's

supervisor, Olik Chaudhuri can be reached on 571-272-1855. The fax phone number for the

organization where this application or proceeding is assigned is 703-872-9306.

32. Information regarding the status of an application may be obtained from the Patent

Application Information Retrieval (PAIR) system. Status information for published applications

may be obtained from either Private PAIR or Public PAIR. Status information for unpublished

applications is available through Private PAIR only. For more information about the PAIR

system, see http://pair-direct.uspto.gov. Should you have questions on access to the Private PAIR

system, contact the Electronic Business Center (EBC) at 866-217-9197 (toll-free).

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WDC